SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Two 8-Bit Back-to-Back Registers Store **Data Flowing in Both Directions**
- **Noninverting Outputs**
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

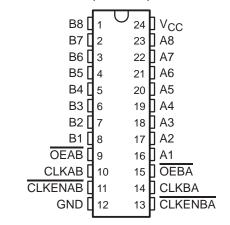
### description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

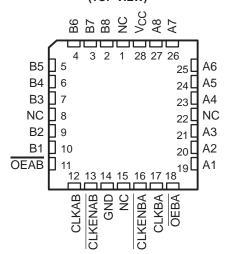
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT2952A is characterized for operation from -40°C to 85°C.

SN54ABT2952A . . . JT OR W PACKAGE SN74ABT2952A...DB, DW, PW, OR NT PACKAGE (TOP VIEW)



#### SN54ABT2952A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



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# SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

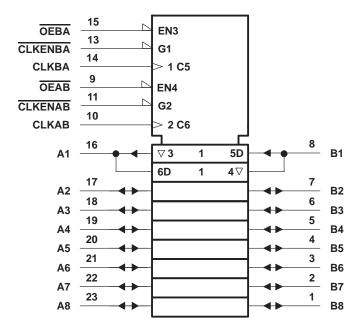
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#### **FUNCTION TABLE**†

	OUTPUT			
CLKENAB	CLKAB	OEAB	Α	В
Н	Х	L	Х	в <sub>0</sub> ‡
Х	H or L	L	Χ	в <sub>0</sub> ‡ в <sub>0</sub> ‡
L	$\uparrow$	L	L	L
L	$\uparrow$	L	Н	Н
Х	Χ	Н	Χ	Z

<sup>†</sup>A-to-B data flow is shown; B-to-A data flow is similar, but uses CLKENBA, CLKBA, and OEBA.

# logic symbol§



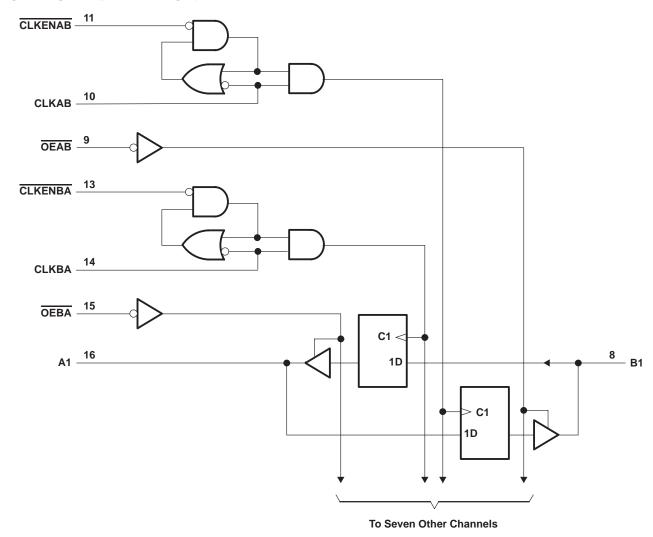
§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



<sup>‡</sup>Level of B before the indicated steady-state input conditions were established

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# logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

# SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>		. $-0.5 \text{ V}$ to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Not		
Voltage range applied to any output in the high or	power-off state, VO	-0.5 V to 5.5 V
Current into any output in the low state, Io: SN54/	ABT2952A	96 mA
SN74/	ABT2952A	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DI	B package	104°C/W
Di	W package	81°C/W
N	T package	67°C/W
P\	W package	120°C/W
Storage temperature range, T <sub>stq</sub>		–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

# recommended operating conditions (see Note 3)

			SN54ABT	2952A	SN74ABT	2952A	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	/IH High-level input voltage				2		V
VIL	Low-level input voltage					0.8	V
٧ı	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
loL	DL Low-level output current					64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		<b>-</b> 55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CO	T <sub>A</sub> = 25°C			SN54ABT2952A		SN74ABT2952A		UNIT	
PARAME	IIEK	TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				v
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
V <sub>hys</sub>					100						mV
	trol inputs	Vcc = 5.5 V,	= 5.5 V, $V_I = V_{CC}$ or GND			±1		±1		±1	μΑ
II A or	B ports	VCC = 5.5 V,				±100		±100		±100	μΑ
lozh <sup>‡</sup>		$V_{CC} = 5.5 V$ ,	$V_0 = 2.7 \text{ V}$			50*		10		50	μΑ
lozL <sup>‡</sup>		$V_{CC} = 5.5 V$ ,	$V_0 = 0.5 V$			-50*		-10		-50	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100*				±100	μΑ
ICEX		V <sub>C</sub> C = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μА
IO§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		$V_{CC} = 5.5 \text{ V},$	Outputs high		1	250		250		250	μΑ
I <sub>CC</sub> A or	A or B ports $I_0 = 0$ ,	$I_O = 0$ , $V_I = V_{CC}$ or	Outputs low		24	35		35		35	mA
	GND GND		Outputs disabled		0.5	250		250		250	μΑ
Δlcc¶		V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1.5		1.5		1.5	mA
C <sub>i</sub> Con	trol inputs	V <sub>I</sub> = 2.5 V or 0.5 \	/		3.5						pF
C <sub>io</sub> A or	B ports	V <sub>O</sub> = 2.5 V or 0.5	V		7.5						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

### timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	clock Clock frequency				150	0	150	0	150	MHz
t <sub>W</sub>	Pulse duration, CLK high or low					3.3		3.3		ns
	Cotur time hafara CLKA	A or B	High or low	2.5		3		2.5		no
t <sub>su</sub>	Setup time before CLK↑	CLKEN	High or low	3		3		3		ns
4.	th Hold time after CLK↑			1.5		1.5		1.5		20
l 'h			CLKEN			2		2		ns

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current. § Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

# SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

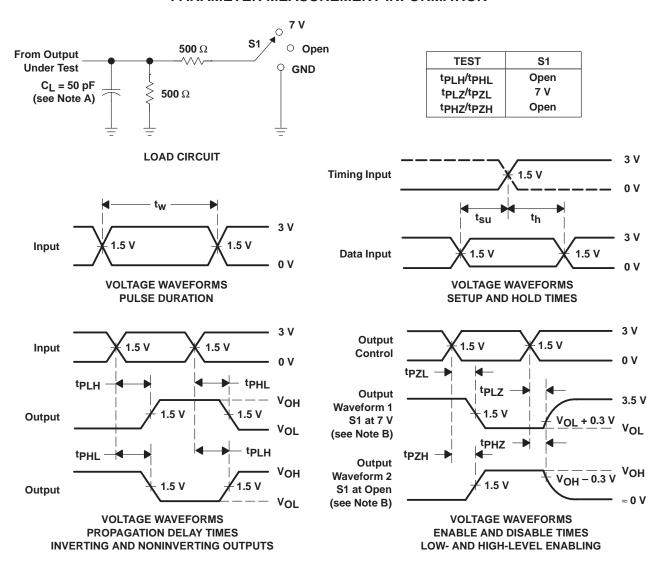
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			150			150		150		MHz
<sup>t</sup> PLH	CLKAB or CLKBA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
<sup>t</sup> PHL	CLNAB OF CLNBA	BULA	2.5	4	6.1	2.5	6.8	2.5	6.3	
<sup>t</sup> PZH	OFDA AT OFAR	A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	ns
tpZL	OEBA or OEAB	AUIB	2	3.7	5.7	2	6.7	2	6.6	115
<sup>t</sup> PHZ	OFDA - OFAR	A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	no
tPLZ	OEBA or OEAB	AUID	1.5	3.4	5.9	1.5	6.7	1.5	6.2	ns



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

#### PACKAGE OPTION ADDENDUM



.com 26-Sep-2005

#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9308602Q3A	ACTIVE	LCCC	FK	28	1	TBD	Call TI	Level-NC-NC-NC
5962-9308602QKA	ACTIVE	CFP	W	24	1	TBD	Call TI	Level-NC-NC-NC
5962-9308602QLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Level-NC-NC-NC
SN74ABT2952ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74ABT2952ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ABT2952ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SNJ54ABT2952AFK	ACTIVE	LCCC	FK	28	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ABT2952AJT	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ABT2952AW	ACTIVE	CFP	W	24	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **PACKAGE OPTION ADDENDUM**

26-Sep-2005

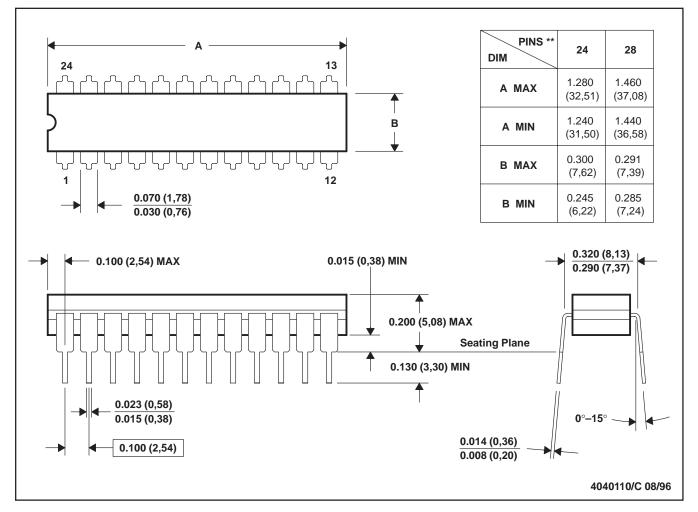
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### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

#### **CERAMIC DUAL-IN-LINE**

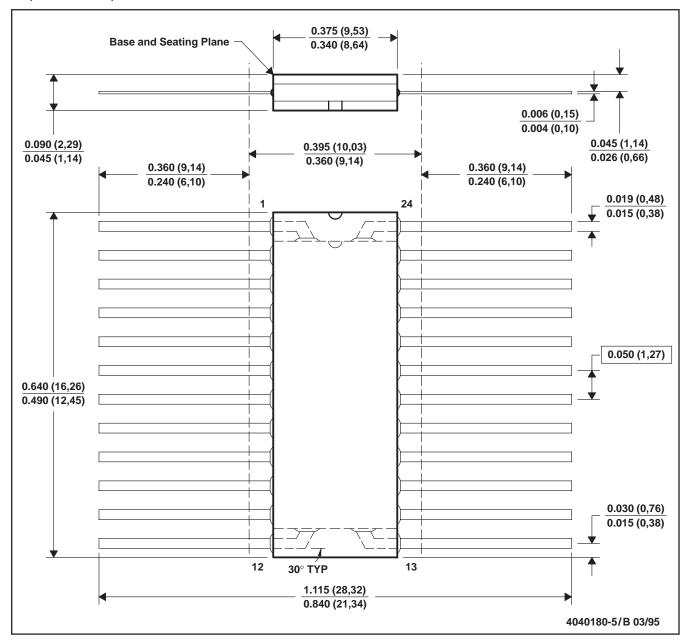


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

### W (R-GDFP-F24)

#### **CERAMIC DUAL FLATPACK**



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - E. Index point is provided on cap for terminal identification only.



### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

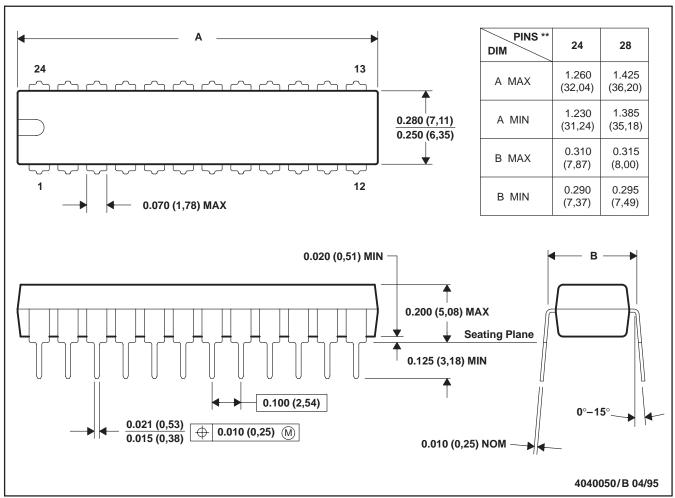
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



### NT (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

#### **24 PINS SHOWN**

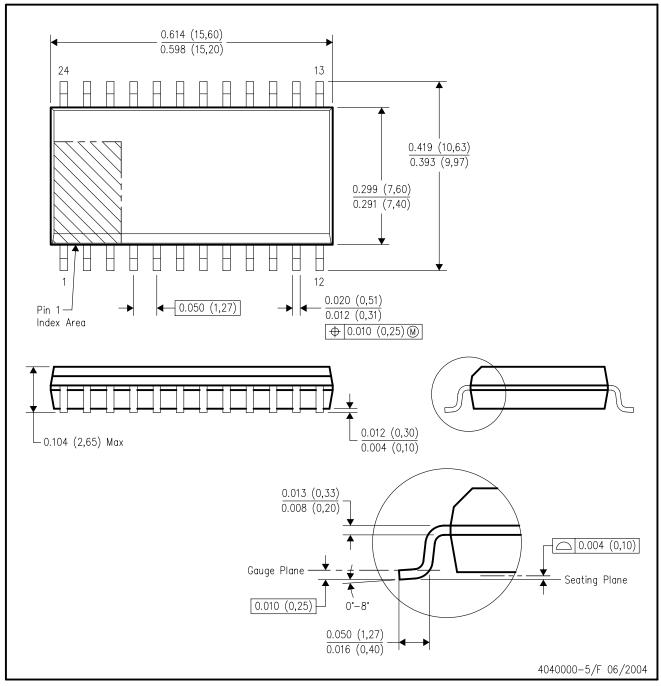


NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

# DW (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# DB (R-PDSO-G\*\*)

# PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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